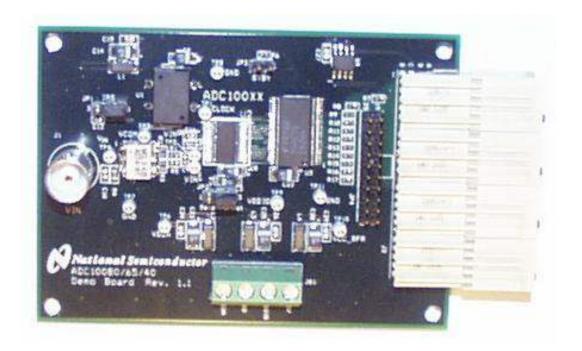


# **Evaluation Board User's Guide**

ADC10040 10-Bit, 40 MSPS, 3 Volt, 55.5 mW A/D Converter ADC10065 10-Bit, 65 MSPS, 3 Volt, 68.5 mW A/D Converter ADC10080 10-Bit, 80 MSPS, 3 Volt, 78.6 mW A/D Converter



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#### 1.0 Introduction

The ADC10080EVAL Design Kit (consisting of the Evaluation Board and this manual) is designed to ease evaluation and design-in of National's ADC10040, ADC10065, or ADC10080 10-bit Analog-to-Digital Converters, which operate at speeds up to 40, 65, and 80 MSPS. Further reference in this manual to the ADC10080 is meant to also include the ADC10040 and the ADC10065 unless otherwise specified. The latest datasheet for these products can be obtained from http://www.national.com.

The evaluation board can be used in either of two modes. In the Manual mode, suitable test equipment, such as a logic analyzer, can be used with the board to evaluate the ADC10080 performance. In the Computer mode, evaluation is simplified by connecting the board to the WaveVision™ Digital Interface Board (order number WAVEVSN BRD 4.0). It is connected to a personal computer through a USB port and running WaveVision™ software, operating under Microsoft Windows 95 or later. The WaveVision™ software can perform an FFT on the captured data upon command and, with the frequency domain plot, shows dynamic performance in the form of SNR, SINAD, THD and SFDR.

The signal at J1, the Analog Input to the board, is digitized and is available at pins B4 through B13 of J2 and pins 10 through 19 of JP4. See the board schematic for more details.

## 2.0 Quick Start

Refer to the board layout for locations of test points and major components.

#### For Stand-Alone operation:

- Select the input voltage range by inserting a jumper into JP1. Set the jumper on pins 1&2 for 2.0 Vpp. Set the jumper on pins 2&3 for 1.5 Vpp. If no jumper is inserted, 1.0 Vpp is assumed.
- To make the ADC10080 active, insure there is no jumper on JP3.
- 3. Select the output data format using JP2. When the jumper is on pins 1&2, 2's complement data format is selected. If the jumper is on pins 2&3, offset binary is selected.
- Connect a clean power supply to Power Connector JS1. Refer to Table 1 for power supply description and requirements.
- Connect a signal of the selected amplitude (see step 1) from a 50-Ohm source to Analog Input BNC J1. Insure that the signal is not over-ranged, by examining a histogram. (Either by using WaveVision<sup>tm</sup>, or the logic analyzer being used.) Over-range signals will dramatically increase the THD.
- The digitized signal is available at pins B4 through B13 of J2 and pins 10 through 19 of JP4.

JS1 pin number	Description	Voltage Range
1	Vcc for Crystal and VDDA for ADC10080	2.7 - 3.3 V
2	Ground	0V
3	VDDIO	2.5 – 3.3 V
4	Output Buffer VCC	4.9 – 5.1 V

Table 1

- Connect the evaluation board to the WaveVision<sup>tm</sup> Digital Interface Board. See the instruction manual supplied with the WaveVision<sup>tm</sup> kit. The latest WaveVision<sup>tm</sup> software can be obtained from http://www.national.com.
- Select the input voltage range by inserting a jumper into JP1.
  Set the jumper on pins 1&2 for 2.0 Vpp. Set the jumper on pins 2&3 for 1.5 Vpp. If no jumper is inserted, 1.0 Vpp is assumed.
- To make the ADC10080 active, insure there is no jumper on JP3.
- 4. Select pins 2&3 on JP2 so that the output data is offset binary.
- Connect a clean power supply to Power Connector JS1. Refer to Table 1 for power supply description and requirements.
- 6. If the output level goes over range as seen on the data captured through WaveVision™, reduce the output level from the signal generator and capture data again. If the output level does not reach codes of 25 and 1000, increase the output level from the signal generator and capture data again.

#### 3.0 Functional Description

The ADC10080 Evaluation Board schematic is shown in Section 5.

#### 3.1 The Signal Input

The signal transformer T1 provides single-ended to differential conversion. The common mode voltage VCOM provided by the chip, sets the common mode of the input signal by biasing the center tap of T1.

The differential signal present on the secondary side of the transformer is then sent through a low pass filter set up by R1, R5 & C9

It is important when evaluating the dynamic performance of the ADC10080 (or any A/D converter), that a clean sine wave be presented to the converter. To do this it is necessary to use a bandpass or a low pass filter between the signal source and the ADC10080 evaluation board input J1. Even the best signal generators available do not provide adequate noise and distortion performance for proper evaluation of a 10-bit ADC. A high-quality bandpass filter with better than 12-bit equivalent noise characteristics and at least 80dB stop band attenuation is ideal. No scope or other test equipment should be connected to any input circuitry while gathering data.

### 3.2 Digital Data Output.

The digital output data from the ADC10080 is available at the 96-pin Euro connector J2 and header JP4. Series resistors R7 – R17 provide data line dampening that may occur with long cables. U3 provides buffering to drive the cable. U3's VCC may be adjusted for various output levels. Refer to Table 1 for voltage range.

#### 3.3 ADC10080 Control Pins.

The ADC10080 has three control pins, making it a very versatile converter. They are Standby (Pin 28 – STBY), Data Format (Pin 15 – DF) and Input Range Select (Pin 5 – IRS).

## 3.3.1The Standby (STBY) Pin

When this pin is pulled high (pins 1&2 of JP3 are connected), the converter is put into 'standby' mode. The converter consumes only 13.5 mW of power. When STBY is tied to VSSA (JP3 is open), the ADC is in full operation.

# 3.3.2 The Data Format (DF) pin

This pin sets the output data format of the ADC10080. When this pin is pulled to VDDA (pins 1&2 of JP2 are connected), the output is 2's complement. When pulled down to VSSA (pins 2&3 of JP2 are connected), the data output is offset binary.

#### 3.3.3 The Input Range Select (IRS) Pin

This pin has three states which the following table summarizes:

JP1 Jumper setting	IRS State	Input Voltage Range (differential)
Pins 1&2	VDDA	2Vpp
Pins 3&4	VSSA	1.5Vpp
Open	Floating	1.0Vpp

## 3.3.4 Power Supply Connections

Power to this board is supplied through power connector JS1. Table 1 describes the pin out, and the allowed voltage ranges

#### **4.0 Obtaining Best Results**

Many factors go into reasonable data capture when evaluating an ADC. These include, but are not limited to, such things as PCB layout, clock timing, the ratio between the input frequency and sample rate and the FFT windowing technique.

Here we include very brief discussions on clock timing adjustments as it relates to the ADC10080 and of sampling and FFT windowing.

#### 4.1 Clock Timing

Because of differing delays in the clock signal and the data from the ADC, at some sample rates the data from the ADC may be latched as it is changing, leading to corrupted data, one example of which is seen in *Figure 2*, which shows the poor data capture of a 4.7MHz signal at 12.5Msps that results from poor timing of the clock and external latch signals relative to each other.

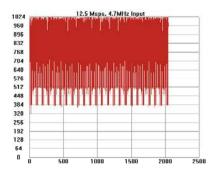


Figure 2. Bad data capture of a 4.7MHz input signal at 12.5Msps due to attempted capture at data transition.

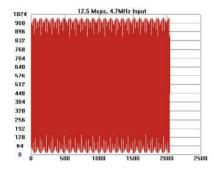


Figure 3. A good data capture of a 4.7MHz input signal at 12.5Msps

### 4.2 Coherent Sampling

Artifacts can result when we perform an FFT on a digitized waveform, producing inconsistent results when performing repeated testing. The presence of these artifacts means that the ADC under test may perform better than the measurements would indicate.

We can eliminate the need for windowing and get more consistent results if we observe the proper ratios between the input and sampling frequencies. This greatly increases the spectral resolution of the FFT, allowing us to more accurately evaluate the spectral response of the A/D converter. When we do this, however, we must be sure that the input signal has high spectral purity and stability and that the sampling clock signal is extremely stable with minimal litter.

Coherent sampling of a periodic waveform occurs when a prime integer number of cycles exists in the sample window. The relationship between the number of cycles sampled (CY), the number of samples taken (SS), the signal input frequency ( $f_{in}$ ) and the sample rate ( $f_{s}$ ), for coherent sampling, is

$$\frac{CY}{SS} = \frac{f_{in}}{f_s}$$

CY, the number of cycles in the data record, must be a prime integer number and SS, the number of samples in the data record, must be a factor of 2 integer.

Further,  $f_{in}$  (signal input frequency) and  $f_{s}$  (sampling rate) should be locked to each other. If these frequencies are locked to each other, whatever frequency instability (jitter) is present in one of the signal is present in the other signal and these jitter terms will cancel each other.

Windowing (an FFT Option under WaveVision<sup>TM</sup>) should be turned off for coherent sampling. The results of coherent sampling can be seen in the FFT plot seen in *Figure 4*. Note how narrow is the bin (how fine are the lines) in this plot as compared with the plots of *Figures 5* through 7.

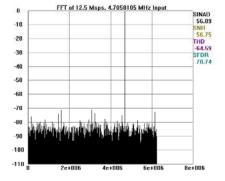


Figure 4. Coherent sampling will indicate accurate dynamic performance of the ADC

## 4.3 FFT Windowing Technique

The FFT assumes the waveform being evaluated is repetitive and that it extends from  $-\infty$  to  $+\infty$  in time. In order to make the evaluated signal appear as though it extends from  $-\infty$  to  $+\infty$ , FFT algorithms fold the signal such that the last point in the data record is followed by the first point. To the extent that this is true, there will be no discontinuities in the folded waveform.

However, folded waveforms often have a discontinuity and this leads to erroneous dynamic performance measurements. This is shown in *Figure 5*, where we see poor, inaccurate dynamic performance measurements at the upper right corner, as well as a spreading around the input frequency. This spreading is called "leakage".

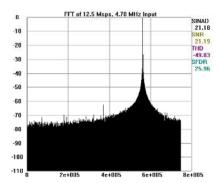


Figure 5. A discontinuity in the folded finite-time waveform leads to misleading results in the FFT.

There are many windowing techniques in use today to minimize this problem. *Figure 6* shows an FFT plot of the same data used in *Figure 5*, but using the Hanning windowing function. Note the improved dynamic performance over no windowing as in *Figure 5*.

The Flat-Top windowing function even yields similar dynamic performance measurements, as can be seen in *Figure 7*. Compare the dynamic performance parameters of *Figures 6 and 7* with those of coherent sampling (*Figure 4*).

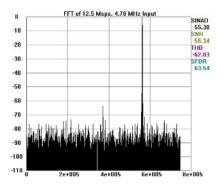


Figure 6. Windowing will reduce the effects of waveform folding. The Hanning windowing function is used here.

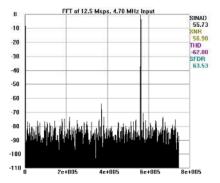
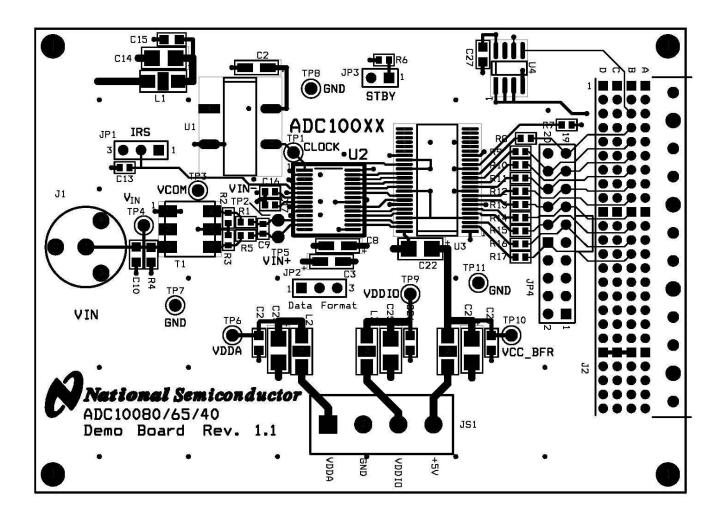
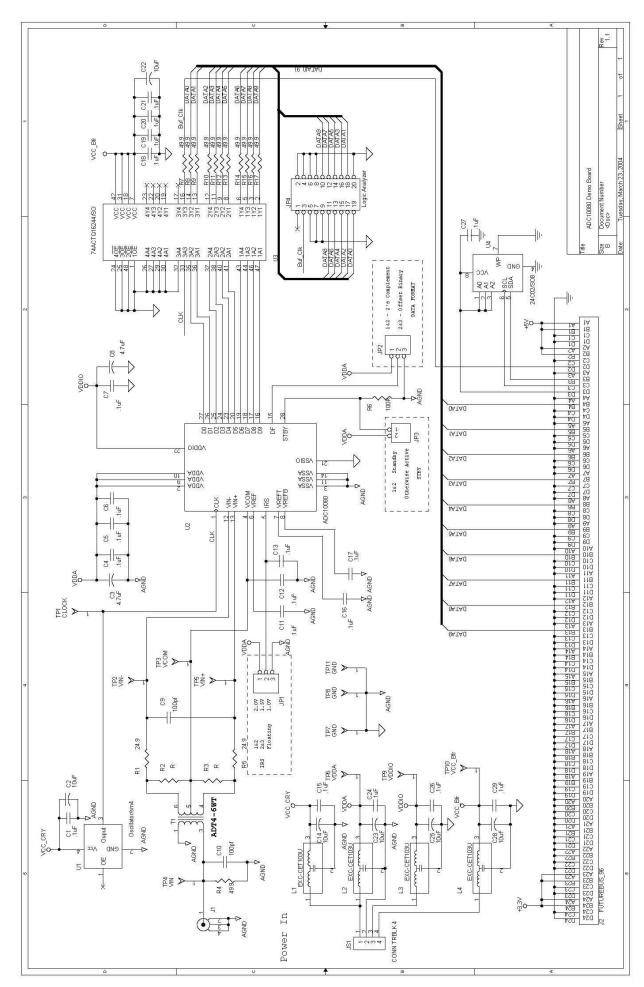


Figure 7. The Flat-Top windowing function yields slightly improved dynamic performance measurements over the Hanning function.

# **5.0 Hardware Documentation**

Please see the attached pages for a board layout, hardware schematic, and Bill of Materials.





Revision: 1.1

# National Semiconductor

# Bill Of Materials

Item	Qty	Reference	Part	
1	10	C1,C7,C15,C18,C19,C20, C21,C24,C26,C29	.1uF	
2	6	C2,C14,C22,C23,C25,C28	10uF	
3	2	C8,C3	4.7uF	
4	8	C4,C5,C6,C11,C12,C13,C16,	.1uF	
5	1	C17 C9	68pf	
6	1	C10	100pf	
7	1	C27	0.1uF	
8	2	JP1,JP2	HEADER 3	
9	1	JP3	HEADER 2	
10	1	JP4	Logic Analyzer	
11	1	JS1	CONN TRBLK 4	
12	1	J1	Vert. PCB mount	
13	1	J2	FUTUREBUS_96	
14	4	L1,L2,L3,L4	EXC-CET103U	
15	4	R1,R5	24.9	
16	1	R4	49.9	
17	1	R6	100K	
18	11	R7,R8,R9,R10,R11,R12,R13,	49.9	
		R14,R15,R16,R17	21 2 21 4	
19	1	TP1	CLOCK	
20	1	TP2	VIN-	
21	1	TP3	VCOM	
22	1	TP4	VIN	
23	1	TP5	VIN+	
24	1	TP6	VDDA	
25	2	TP7,TP8	GND	
26	1	TP9	VDDIO	
27	1	TP10	VCC_Bfr	
28	1	T1	TRANSFORMER CT	
29	1	U1	Oscillator/sm4	
30	1	U2	ADC10080	
31	1	U3	74ACTQ16244/SO	
32	1	U4	24C02/SO8	
33	2	R2,R3	NP	

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